



TotalEnergies

Refining & Chemicals
Polymers

Polypropylene Lumicene® MH35YN9

Technical data sheet
Polypropylene – Metallocene Homopolymer
Produced in Europe

Description

Polypropylene Lumicene® MH35YN9 is a metallocene polypropylene with a Melt Flow Index of 36 g/10 min and with an anti gas-fading formulation.

Polypropylene Lumicene® MH35YN9 is designed for the spunbond process and intended for hygiene nonwovens applications. It combines the usual advantages of metallocene catalysis with a higher fluidity, which makes it particularly suitable for the production of spunlaid nonwovens having an improved balance between processability and nonwoven properties (such as fine titer, good web coverage, and/or mechanical properties).

Characteristics

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133	g/10 min	36
Mechanical properties			
Flexural modulus	ISO 178	MPa	1400
Thermal properties			
Melting Point	ISO 3146	°C	151
Other physical properties			
Density	ISO 1183	g/cm ³	0.905
Bulk Density	ISO 1183	g/cm ³	0.525

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

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